

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1458	(@ad<"20010110") and (mold or molding or dice or plate or die) and (wafer with (cap or lid or sink or spreader))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 12:19
L2	118	L1 and ((mold or molding or dice or plate or die) near (semiconductor or silicon or "si"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 12:11
L3	0	I2 NOT I1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 09:51
L4	1340	I1 NOT L2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 09:51
L5	36	("5824177").URPN.	USPAT	OR	OFF	2005/06/23 10:50
L6	7	("6429506").URPN.	USPAT	OR	OFF	2005/06/23 10:54
L7	0	("6759273").URPN.	USPAT	OR	OFF	2005/06/23 10:54
L8	15	("4791075"   "4907065"   "5150196"   "5323051"   "5362681"   "5435876"   "5610431"   "5824177"   "5831162"   "6106735"   "6109113"   "6210514"   "6410360"   "6429506"   "6555417").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/23 10:54
L9	64	("4701999").URPN.	USPAT	OR	OFF	2005/06/23 11:28
L10	7	("3714370"   "3838094"   "4303934"   "4305897"   "4535350").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/23 11:33
L11	22	(@ad<"20010110") and (wafer near (cap or lid or sink or spreader)) and pin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 11:48

L12	39	(@ad<"20010110") and (wafer near (cap or lid or sink or spreader)) and pin\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 11:53
L13	11	L12 not L1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 11:48
L14	5	(@ad<"20010110") and (wafer near (cap or lid or sink or spreader)) and protrusion	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 11:50
L15	0	(@ad<"20010110") and (wafer near (cap or lid or sink or spreader)) and ((pin\$1 or protrusion) with (release and ( molding or dice or die or mold )))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 11:52
L16	687	(@ad<"20010110") and (chip or die or wafer) and ((pin\$1 or protrusion) with (release and ( molding or dice or die or mold )))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 11:53
L17	684	L16 not L1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 11:53
L18	0	L17 and (wafer near (cap or lid or sink or spreader))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 11:53
L19	19	L1 and ((mold or molding or dice or plate or die) near (etch or etching or lithography or photolithography))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 12:18

L20	207	(encapsulant or encapsulate or encapsulating) and ((mold or molding or dice or plate or die) near (etch or etching or lithography or photolithography))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 12:19
L21	103	L20 and (@ad<"20010110")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 12:20